

L Number	Hits	Search Text	DB	Time stamp
1	3005	wafer same level same (package packaging packaged)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/02/22 15:54
2	96	(trench groove) same (wafer same level same (package packaging packaged))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/02/22 15:55

L Number	Hits	Search Text	DB	Time stamp
1	10877	wafer same trench	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/22 15:23
2	210	(wafer same trench) same (packaging packages packaged)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/22 15:24
3	51047	chip with size	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/22 15:24
4	69	((wafer same trench) same (packaging packages packaged)) and (chip with size)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/22 15:24